

NLX2G14

Dual Schmitt-Trigger Inverter

The NLX2G14 MiniGate™ is an advanced high-speed CMOS dual Schmitt-trigger inverter in ultra-small footprint.

The NLX2G14 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

The NLX2G14 can be used to enhance noise immunity or to square up slowly changing waveforms.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^\circ C$
- 24 Balanced Output Source and Sink Capability
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

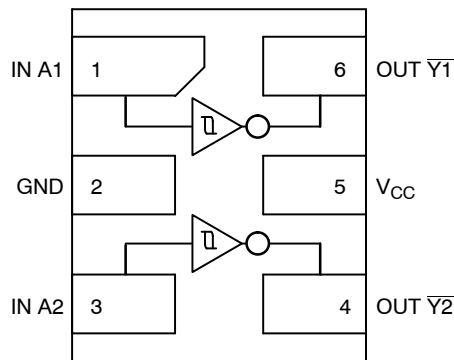


Figure 1. Pinout (Top View)

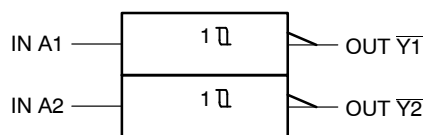


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V_{CC}
6	OUT Y1

FUNCTION TABLE

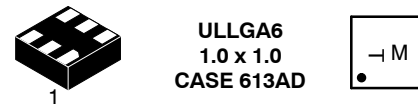
A	\bar{Y}
L	H
H	L



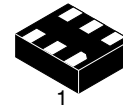
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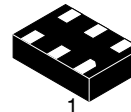
MARKING DIAGRAMS



ULLGA6
1.0 x 1.0
CASE 613AD



ULLGA6
1.2 x 1.0
CASE 613AE



ULLGA6
1.45 x 1.0
CASE 613AF



UDFN6
1.0 x 1.0
CASE 517BX



UDFN6
1.2 x 1.0
CASE 517AA



UDFN6
1.45 x 1.0
CASE 517AQ



T = Device Marking*

M = Date Code

* Rotated 90° clockwise

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

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MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage	-0.5 to +7.0	V
I _{IK}	DC Input Diode Current V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current V _{OUT} < GND	-50	mA
I _O	DC Output Source/Sink Current	±50	mA
I _{CC}	DC Supply Current Per Supply Pin	±100	mA
I _{GND}	DC Ground Current per Ground Pin	±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125 °C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/UESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate V _{CC} = 3.3 V ± 0.3 V V _{CC} = 5.0 V ± 0.5 V	0 0	No Limit No Limit	ns/V

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25 °C			T _A = +85°C		T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V _{T+}	Positive Threshold Voltage		1.65	0.6	1.0	1.4	0.6	1.4	0.6	1.4	V
			2.3	1.0	1.5	1.8	1.0	1.8	1.0	1.8	
			2.7	1.2	1.7	2.0	1.2	2.0	1.2	2.0	
			3.0	1.3	1.9	2.2	1.3	2.2	1.3	2.2	
			4.5	1.9	2.7	3.1	1.9	3.1	1.9	3.1	
			5.5	2.2	3.3	3.6	2.2	3.6	2.2	3.6	
V _{T-}	Negative Threshold Voltage		1.65	0.2	0.5	0.8	0.2	0.8	0.2	0.8	V
			2.3	0.4	0.75	1.15	0.4	1.15	0.4	1.15	
			2.7	0.5	0.87	1.4	0.5	1.4	0.5	1.4	
			3.0	0.6	1.0	1.5	0.6	1.5	0.6	1.5	
			4.5	1.0	1.5	2.0	1.0	2.0	1.0	2.0	
			5.5	1.2	1.9	2.3	1.2	2.3	1.2	2.3	
V _H	Hysteresis Voltage		1.65	0.1	0.48	0.9	0.1	0.9	0.1	0.9	V
			2.3	0.25	0.75	1.1	0.25	1.1	0.25	1.1	
			2.7	0.3	0.83	1.15	0.3	1.15	0.3	1.15	
			3.0	0.4	0.93	1.2	0.4	1.2	0.4	1.2	
			4.5	0.6	1.2	1.5	0.6	1.5	0.6	1.5	
			5.5	0.7	1.4	1.7	0.7	1.7	0.7	1.7	
V _{OH}	Minimum High-Level Output Voltage	V _{IN} ≤ V _{T-MIN} I _{OH} = -100 μA	1.65- 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V _{CC} - 0.1		V
		V _{IN} ≤ V _{T-MIN} I _{OH} = -4 mA	1.65	1.29	1.52		1.29		1.29		
		I _{OH} = -8 mA	2.3	1.9	2.1		1.9		1.8		
		I _{OH} = -12 mA	2.7	2.2	2.4		2.2		2.1		
		I _{OH} = -16 mA	3.0	2.4	2.7		2.4		2.3		
		I _{OH} = -24 mA	3.0	2.3	2.5		2.3		2.2		
		I _{OH} = -32 mA	4.5	3.8	4.0		3.8		3.7		
V _{OL}	Maximum Low-Level Output Voltage	V _{IN} ≥ V _{T+MAX} I _{OL} = 100 μA	1.65- 5.5		0	0.1		0.1		0.1	V
		V _{IN} ≥ V _{T+MAX} I _{OH} = -4 mA	1.65		0.08	0.24		0.24		0.24	
		I _{OH} = -8 mA	2.3		0.2	0.3		0.3		0.4	
		I _{OH} = -12 mA	2.7		0.22	0.4		0.4		0.5	
		I _{OH} = -16 mA	3.0		0.28	0.4		0.4		0.5	
		I _{OH} = -24 mA	3.0		0.38	0.55		0.55		0.55	
		I _{OH} = -32 mA	4.5		0.42	0.55		0.55		0.65	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	0 to 5.5			±0.1		±1.0		μA	
I _{OFF}	Power-Off Output Leakage Current	V _{OUT} = 5.5 V	0			1.0		10		μA	
I _{CC}	Quiescent Supply Current	0 ≤ V _{IN} ≤ V _{CC}	5.5			1.0		10		μA	

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AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns)

Symbol	Parameter	V_{CC} (V)	Test Condition	$T_A = 25^\circ\text{C}$			$T_A = +85^\circ\text{C}$		$T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay, Input A to Output Y	2.3–2.7	$R_L = 1\text{ M}\Omega$, $C_L = 15\text{ pF}$	1.8	4.3	7.4	1.8	8.1	1.8	9.1	ns
		3.0–3.6	$R_L = 1\text{ M}\Omega$, $C_L = 15\text{ pF}$	1.5	3.3	5.0	1.5	5.5	1.5	6.5	
				$R_L = 500\ \Omega$, $C_L = 50\text{ pF}$	1.8	4.0	6.0	1.8	6.6	1.8	
		4.5–5.5	$R_L = 1\text{ M}\Omega$, $C_L = 15\text{ pF}$	1.0	2.7	4.1	1.0	4.5	1.0	5.5	
				$R_L = 500\ \Omega$, $C_L = 50\text{ pF}$	1.2	3.2	4.9	1.2	5.4	1.2	
C_{IN}	Input Capacitance	5.5	$V_{IN} = 0\text{ V}$ or V_{CC}		2.5						pF
C_{PD}	Power Dissipation Capacitance (Note 6)	3.3 5.5	10 MHz $V_{IN} = 0\text{ V}$ or V_{CC}		11 12.5						pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

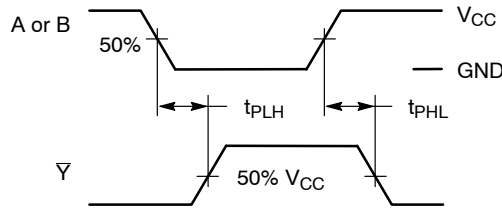
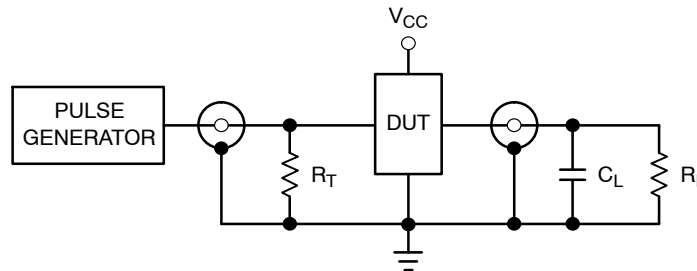


Figure 3. Switching Waveforms



$R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

NLX2G14

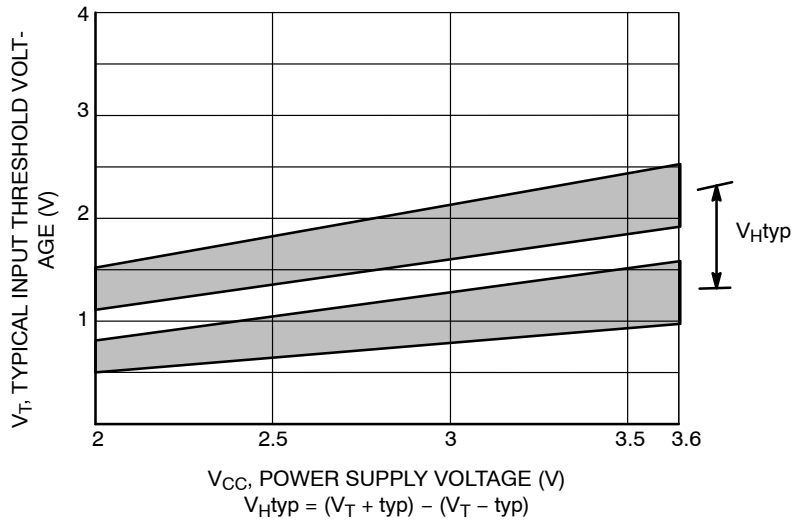
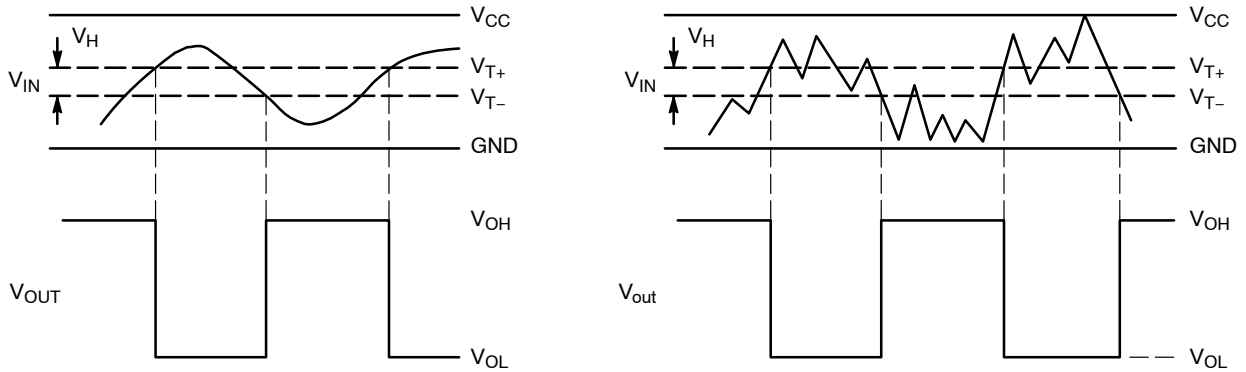


Figure 5. Typical Input Threshold, V_{T+} , V_{T-} versus Power Supply Voltage



(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times

(b) A Schmitt-Trigger Offers Maximum Noise Immunity

Figure 6. Typical Schmitt-Trigger Applications

ORDERING INFORMATION

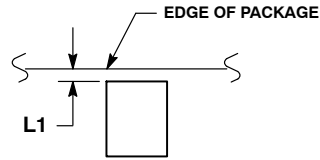
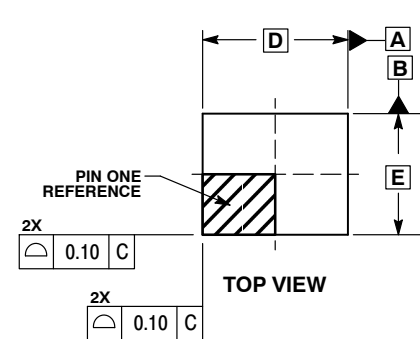
Device	Package	Shipping [†]
NLX2G14AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G14BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G14CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel
NLX2G14MUTCG In Development	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G14AMUTCG In Development	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G14CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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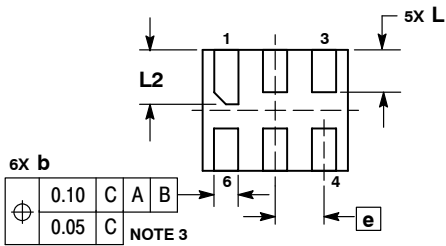
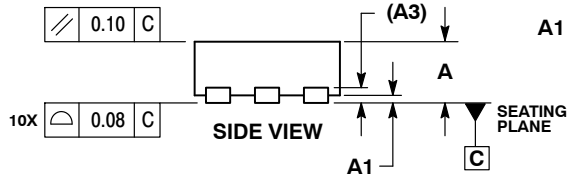
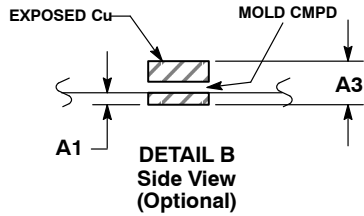
PACKAGE DIMENSIONS

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CASE 517AA
ISSUE D

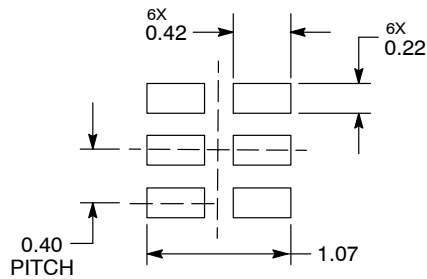


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	1.20	BSC
E	1.00	BSC
e	0.40	BSC
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50



MOUNTING FOOTPRINT*



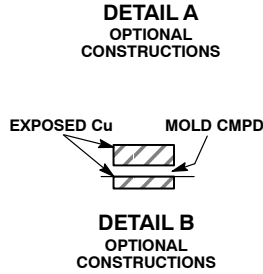
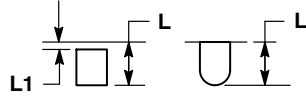
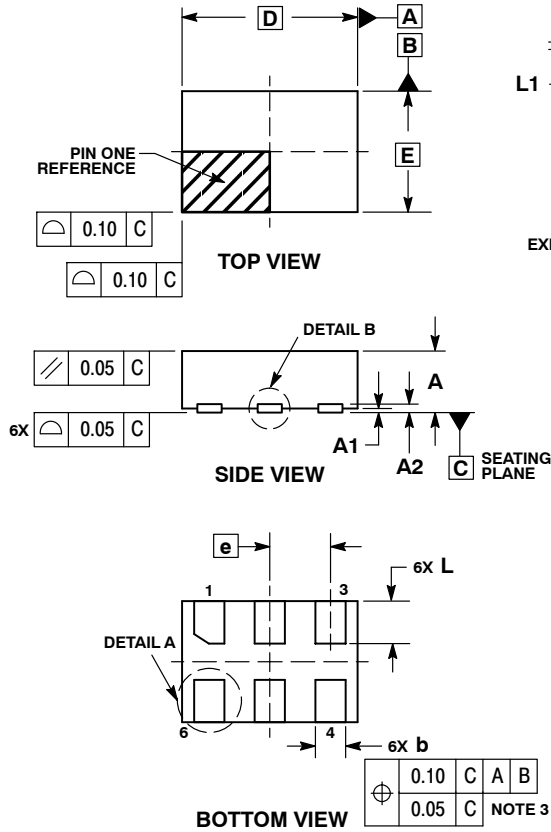
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NLX2G14

PACKAGE DIMENSIONS

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CASE 517AQ
ISSUE O

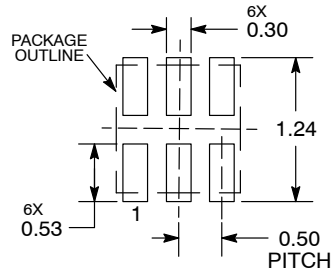


NOTES:

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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



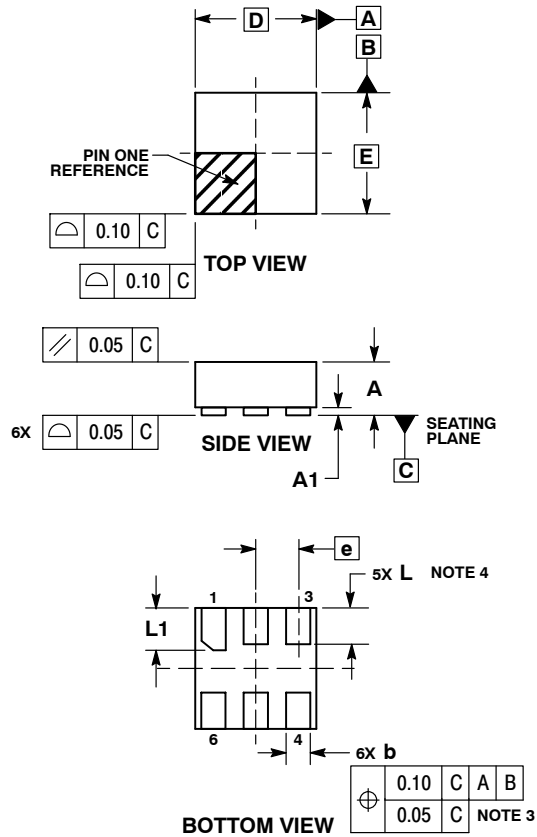
DIMENSIONS: MILLIMETERS

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NLX2G14

PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P
CASE 613AD
ISSUE A

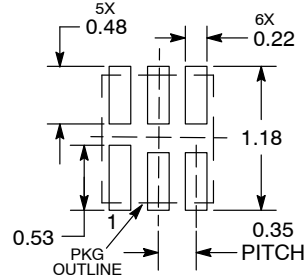


NOTES:

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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

**MOUNTING FOOTPRINT
SOLDERMASK DEFINED***



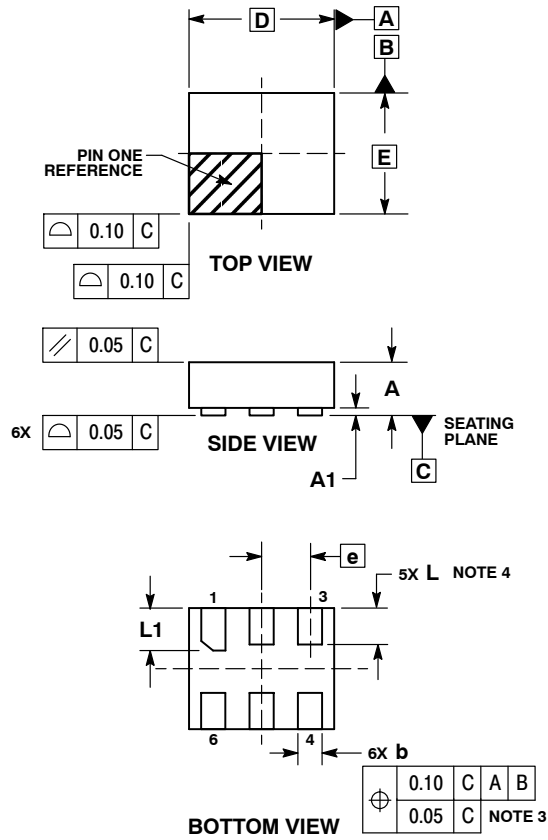
DIMENSIONS: MILLIMETERS

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NLX2G14

PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P
CASE 613AE
ISSUE A

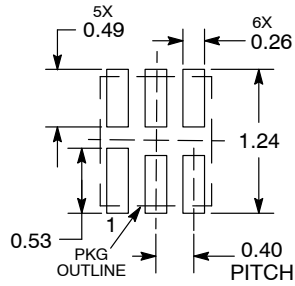


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MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

**MOUNTING FOOTPRINT
SOLDERMASK DEFINED***



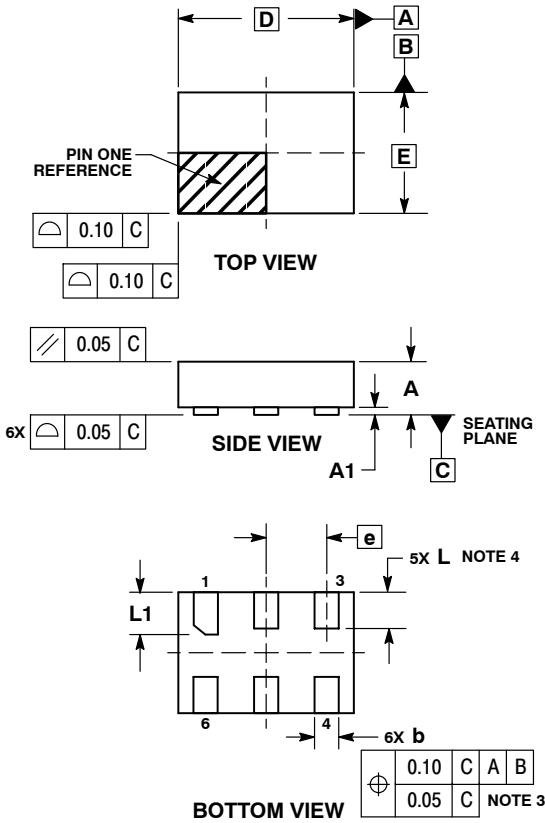
DIMENSIONS: MILLIMETERS

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PACKAGE DIMENSIONS

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CASE 613AF
ISSUE A

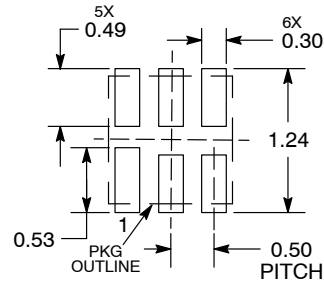


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MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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